

# TPA Laser Experiment on the MPW2 HVCMOS MAPS chip

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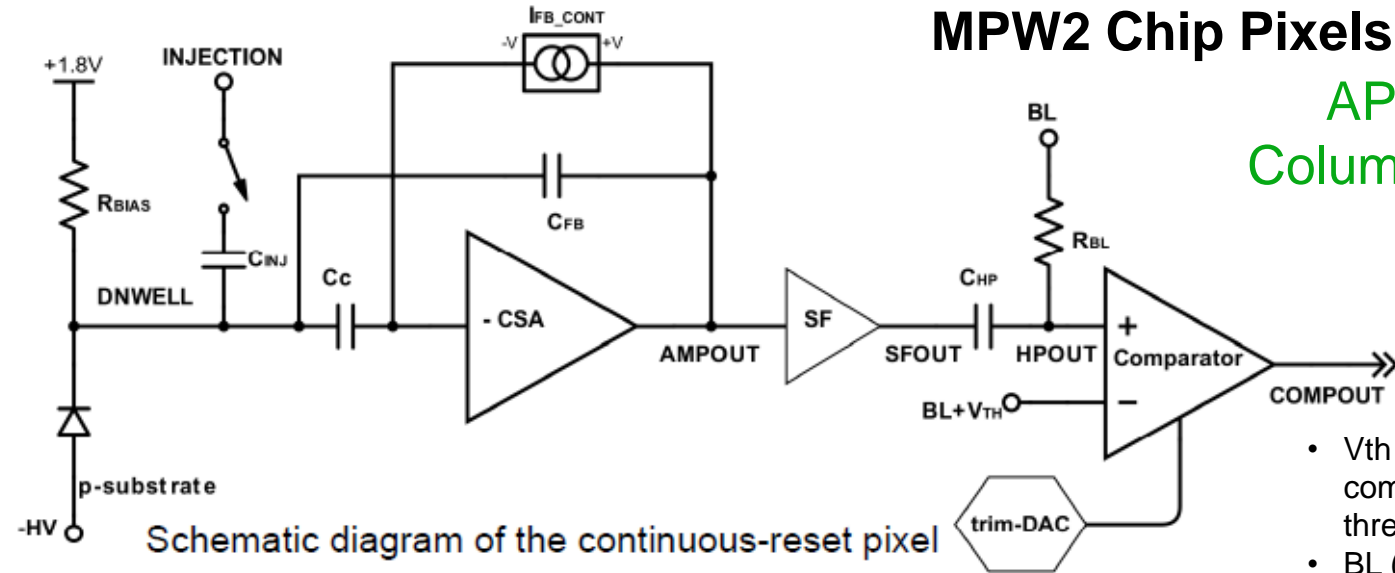


Dec 2<sup>nd</sup> 2022 <https://indico.cern.ch/event/1132520/>



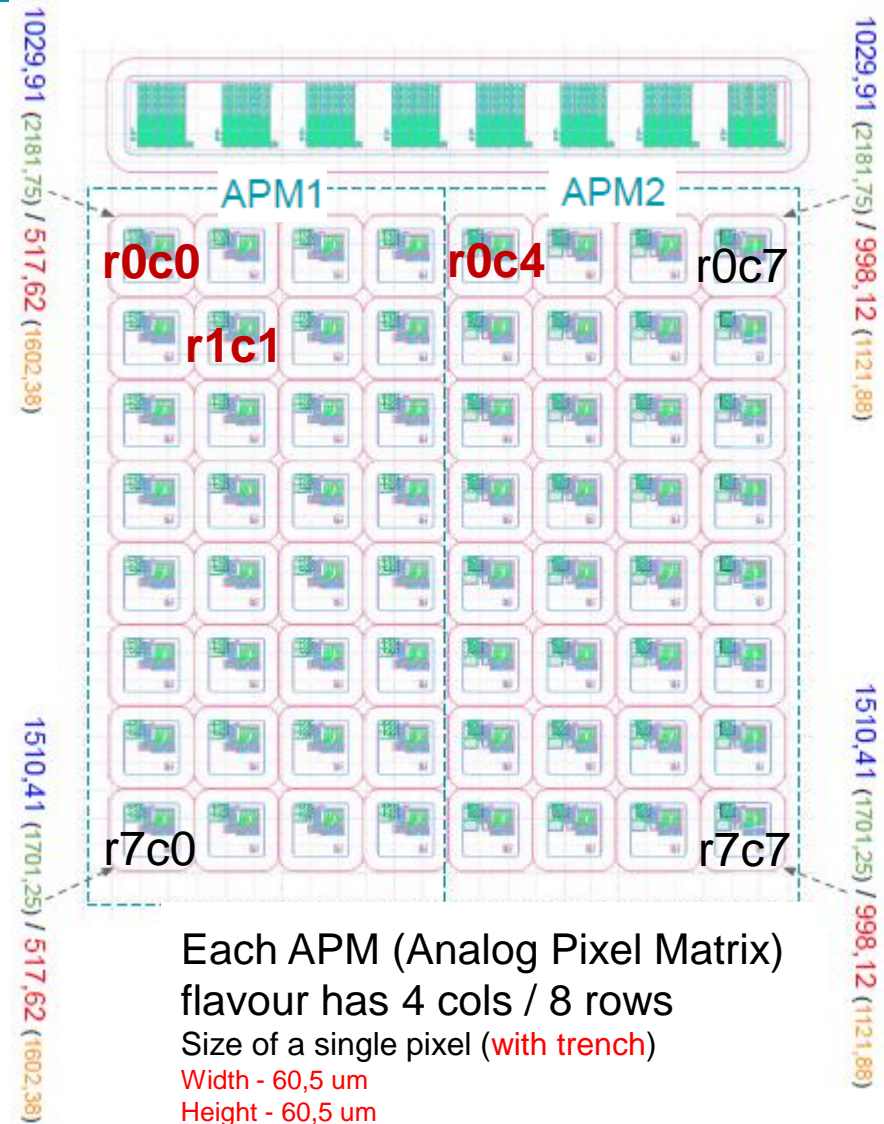
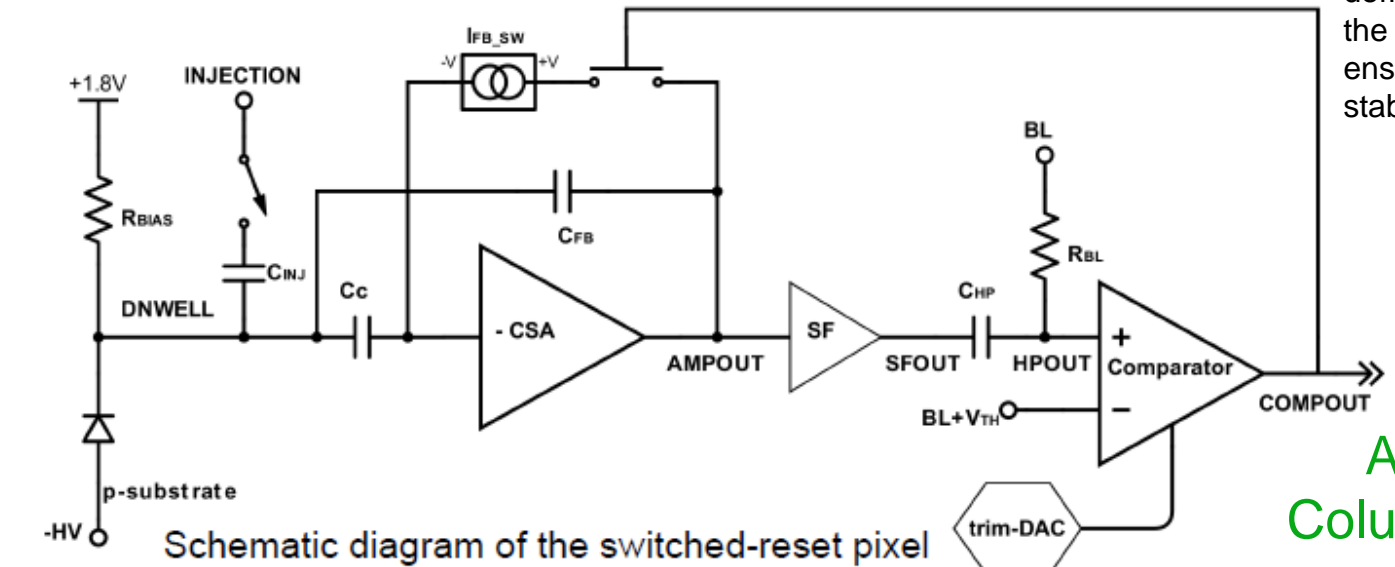
## MPW2 Chip Pixels

APM1  
Columns 0-3



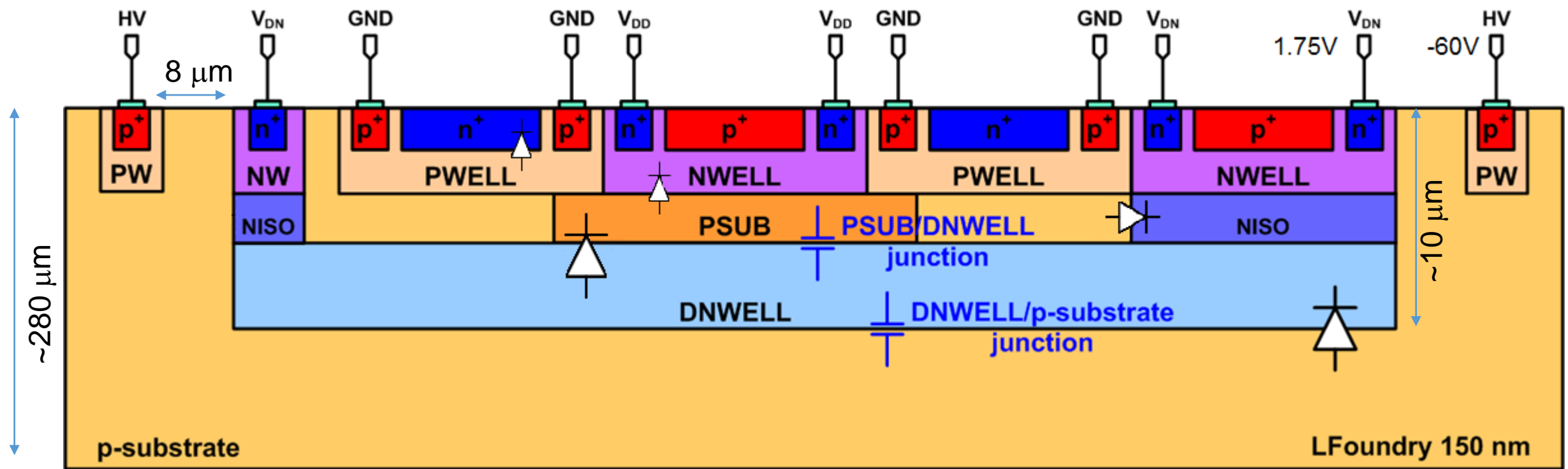
- $V_{th}$  defines the comparator threshold
- BL (baseline) defines an offset to the analog output to ensure signal stability

APM2  
Columns 4-7

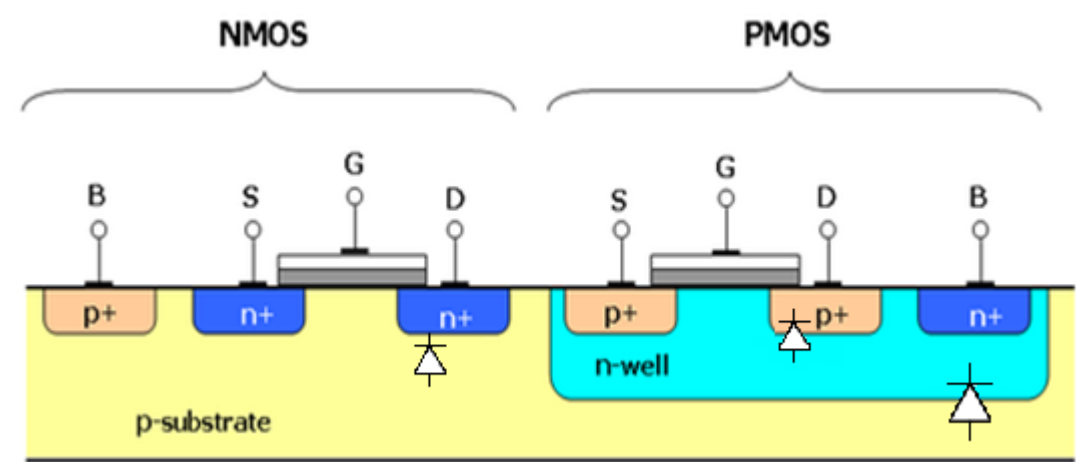


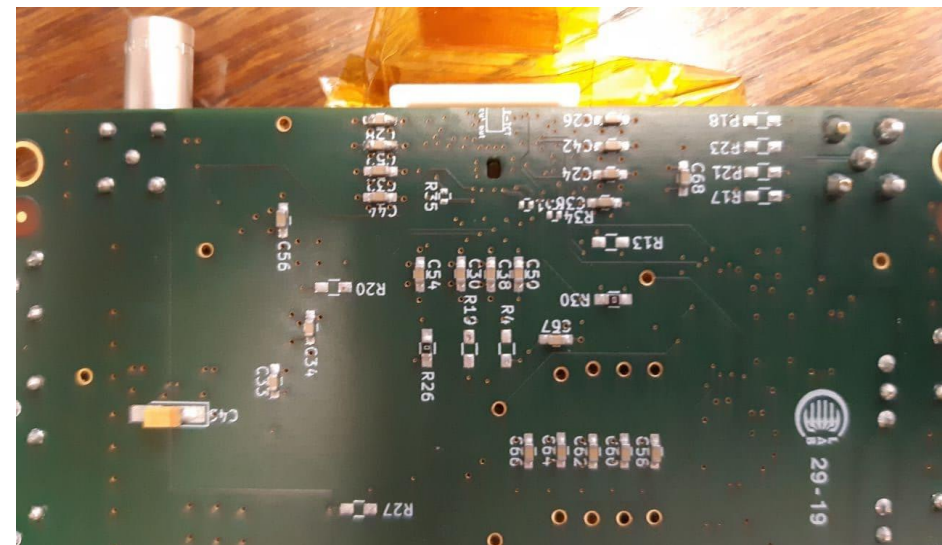
Each APM (Analog Pixel Matrix) flavour has 4 cols / 8 rows  
 Size of a single pixel (with trench)  
 Width - 60,5 um  
 Height - 60,5 um  
 Size of a single pixel (without trench)  
 Width - 39,68 um    Trench<sub>w</sub> - 20,3 um  
 Height - 39,68 um    Trench<sub>H</sub> - 20,3 um

# General Description



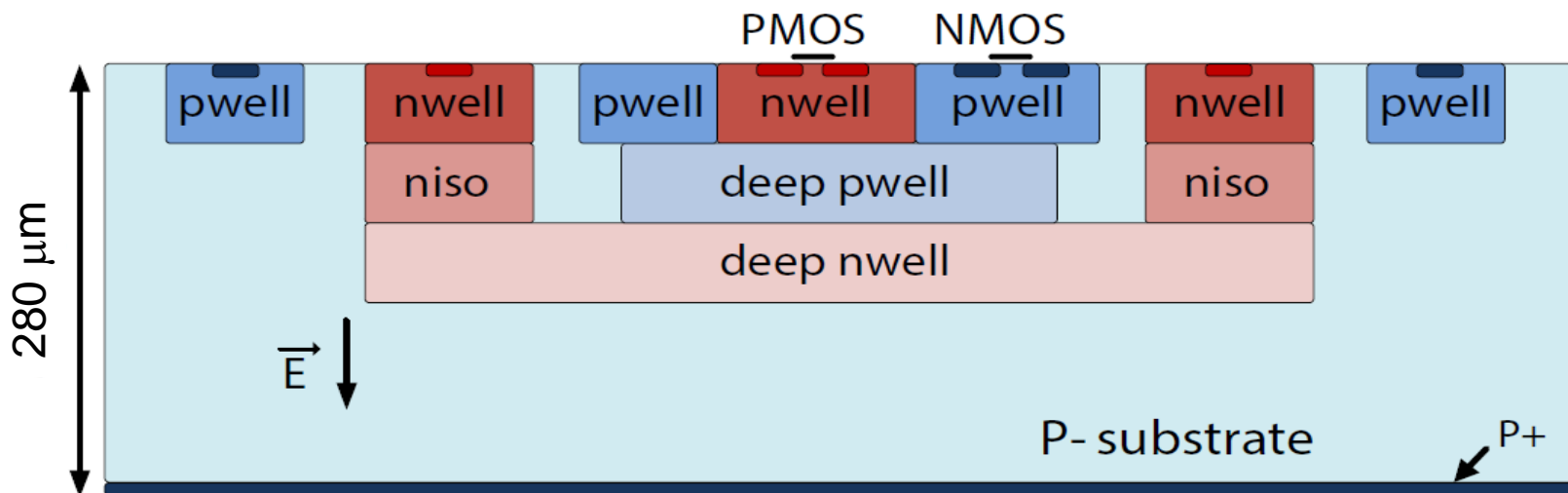
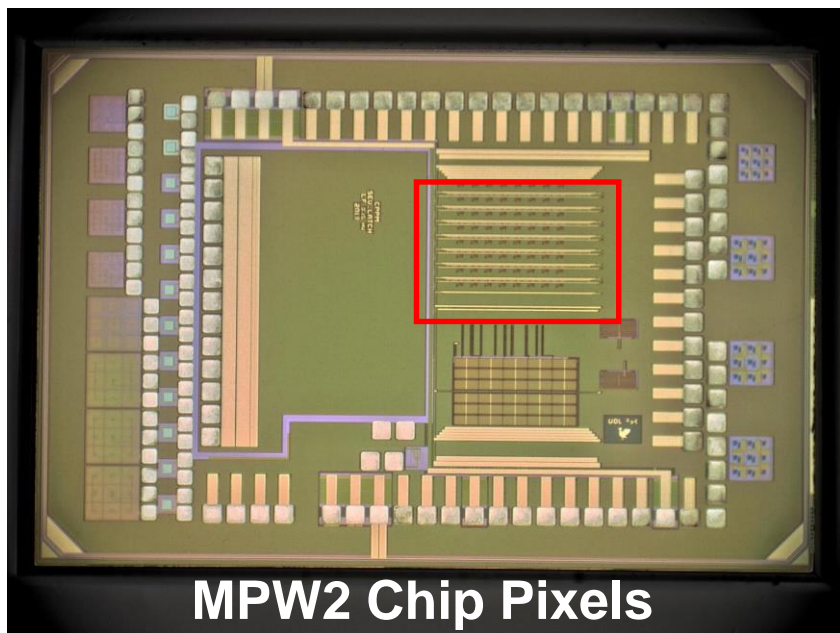
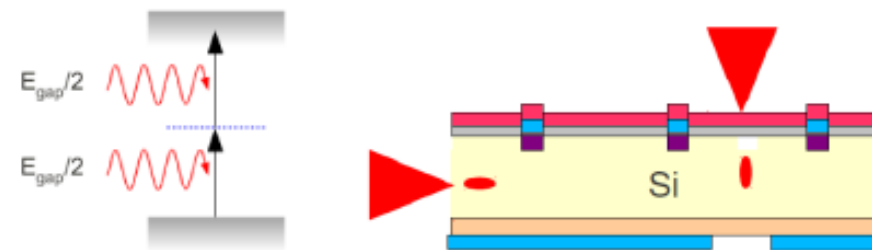
The experiment purpose is to get signals from the chip under femtosecond TPA laser excitation at different chip depths (z-scan mode). The hope is to get signals from every pixel layer in order to classify them as proper detections (dnwell-psubs diode), parasitic detections (other inter-layers reverse biased pn diodes) or single event effects (laser voxel in the electronics zone, near to the die Surface, signal produced by the pn isolating diodes between the diffusion and the embedding well )



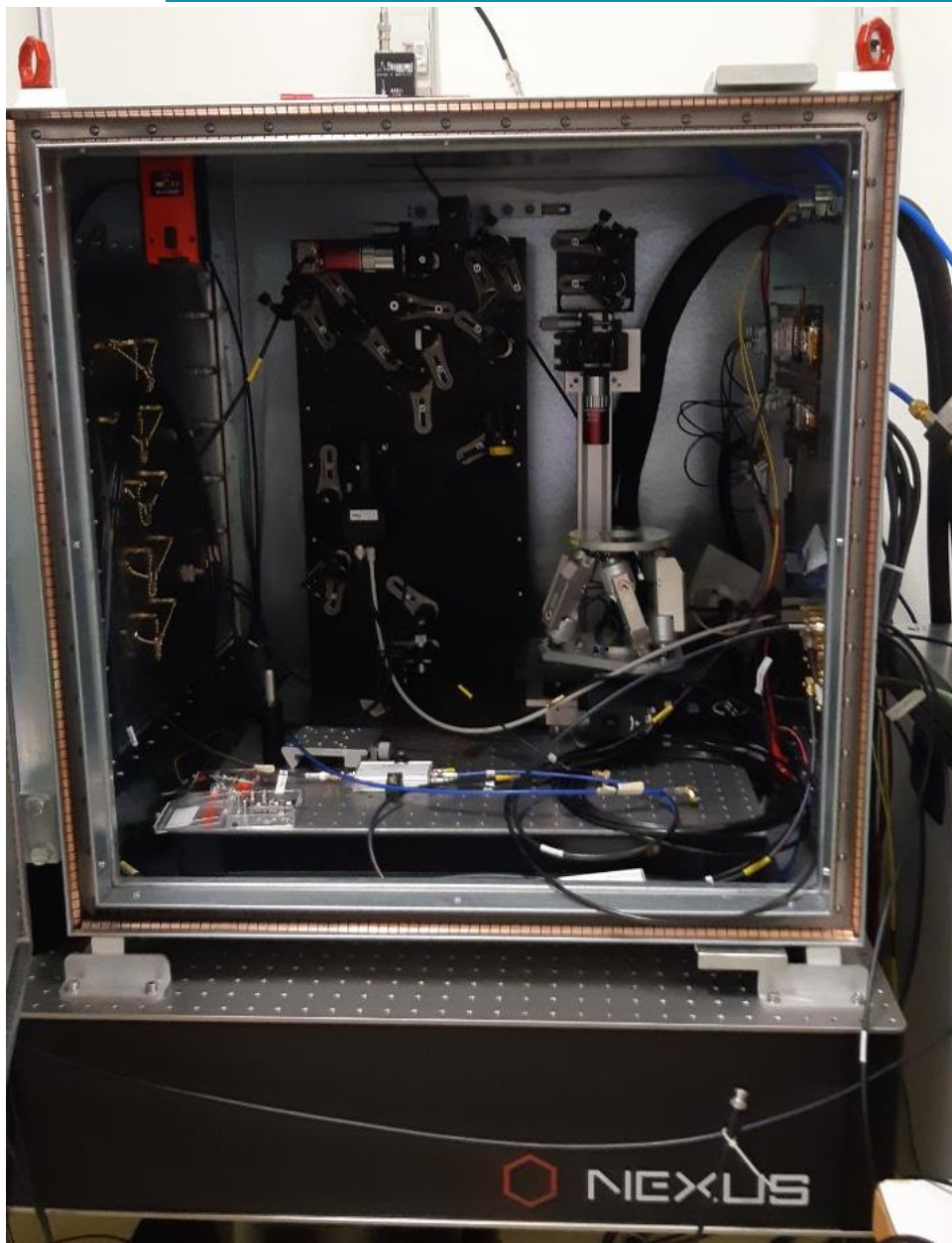


The MPW2 card has a window to the MPW2 chip, designed for backside laser illumination. At 1550 nm, 400 fs, the silicon is transparent below a light intensity threshold so the photoionization (light absorption) happens only around the focus point (voxel volume). A z-scan means to precisely position the voxel volumen along different die depths, also moving the beam along the pixel area. That way any particular volume can be excited to generate a signal in the collecting electrodes.

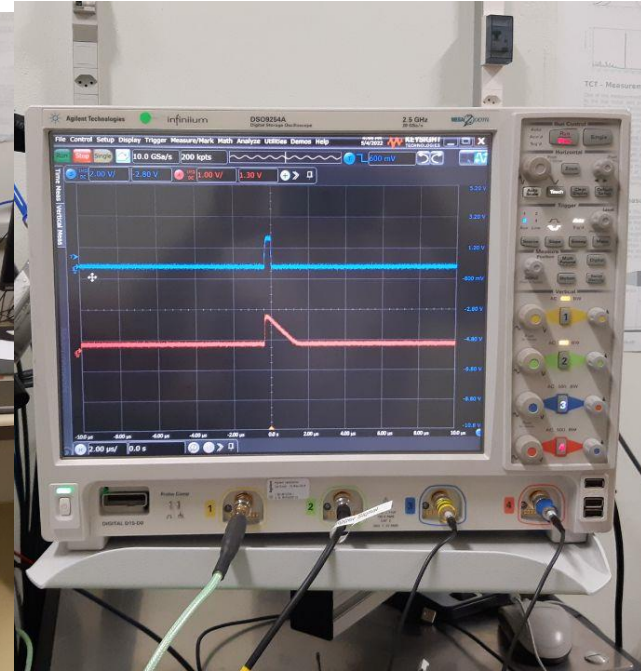
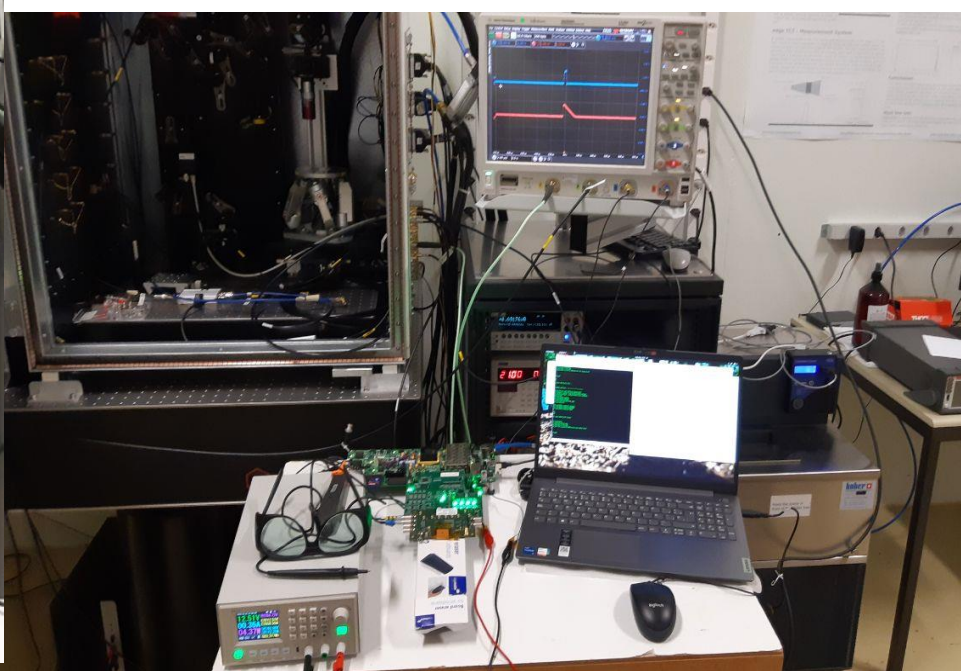
8x8 active pixel matrix  
 60x60  $\mu\text{m}^2$  pixel size  
 1.9  $\text{k}\Omega\text{-cm}$  substrate resistivity  
 no backside metallization

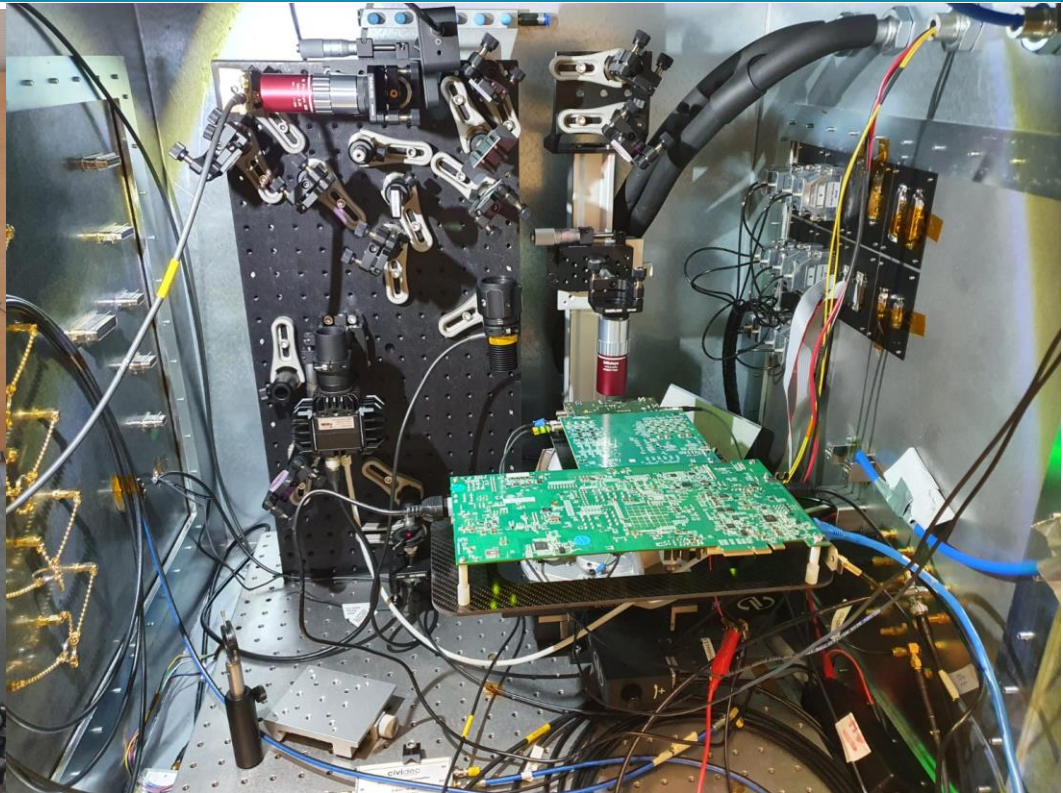


# General Description



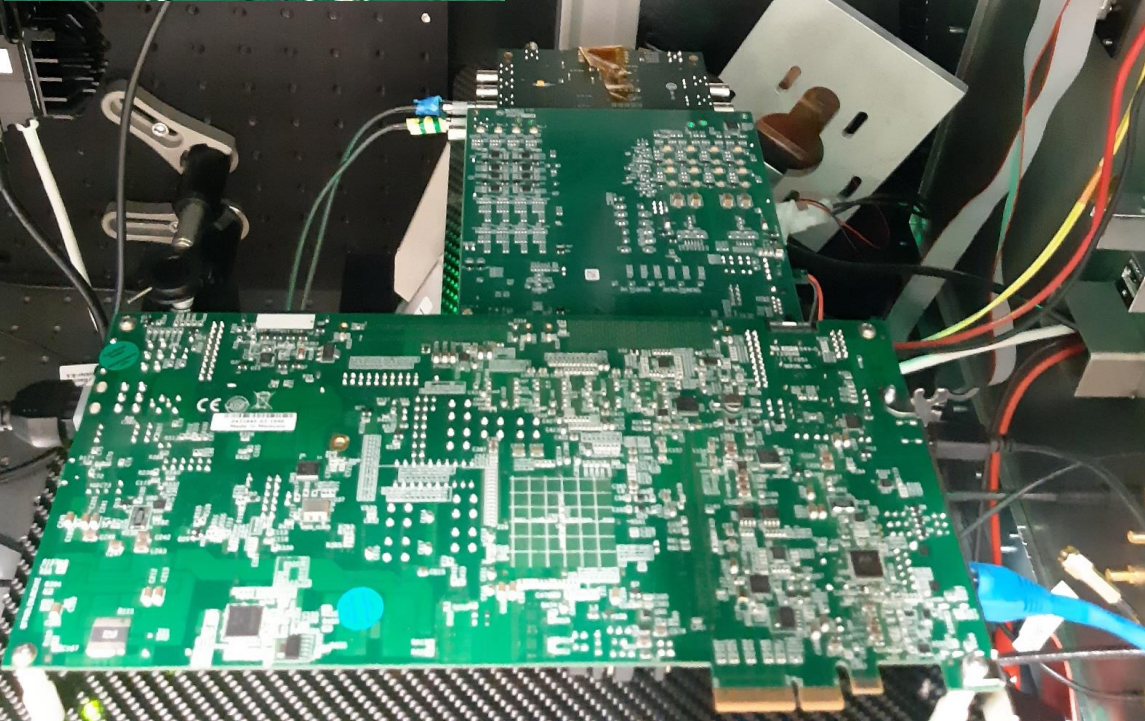
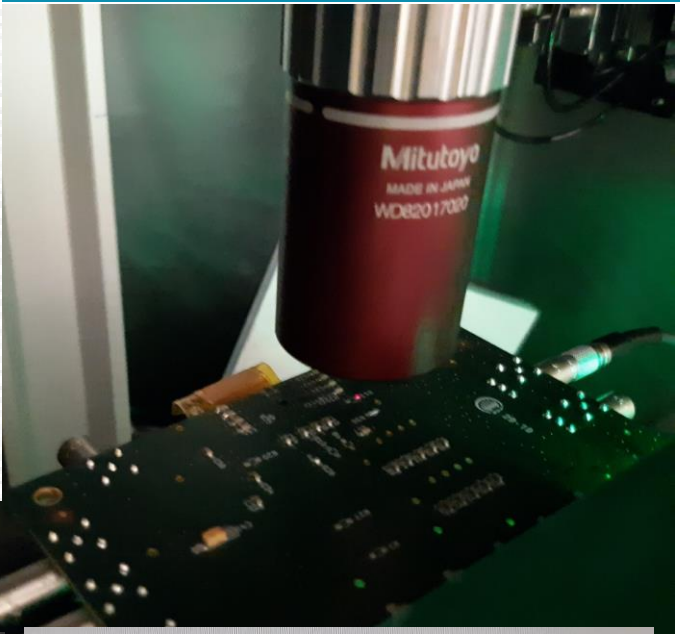
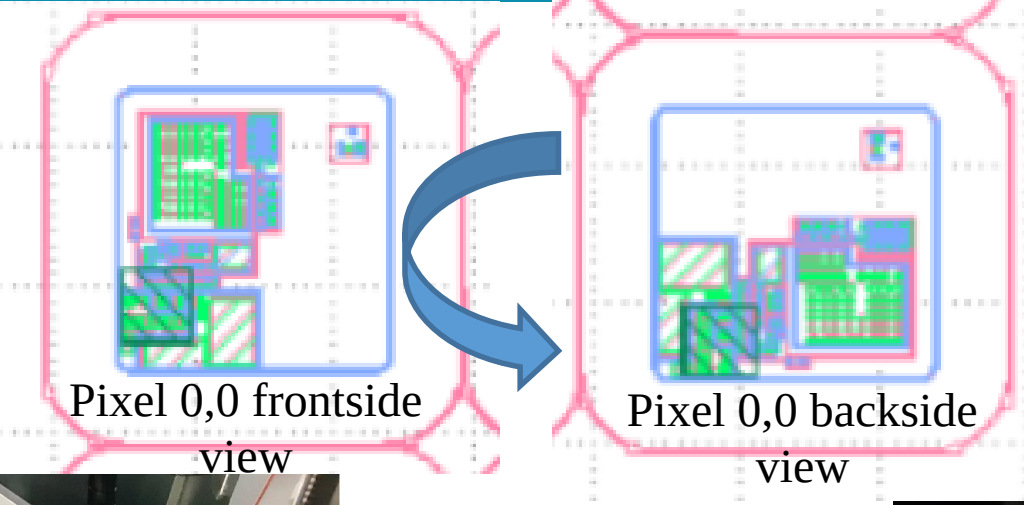
SSD Laser for TPA  
 1550 nm, ~400 fs,  
 magnetoacoustic pulse  
 picker (selectable single  
 shots). Different depths  
 by focusing, different  
 XY positions by a hexa-  
 pod platform, EMI iso-  
 lated, batiment 28  
 basement@CERN



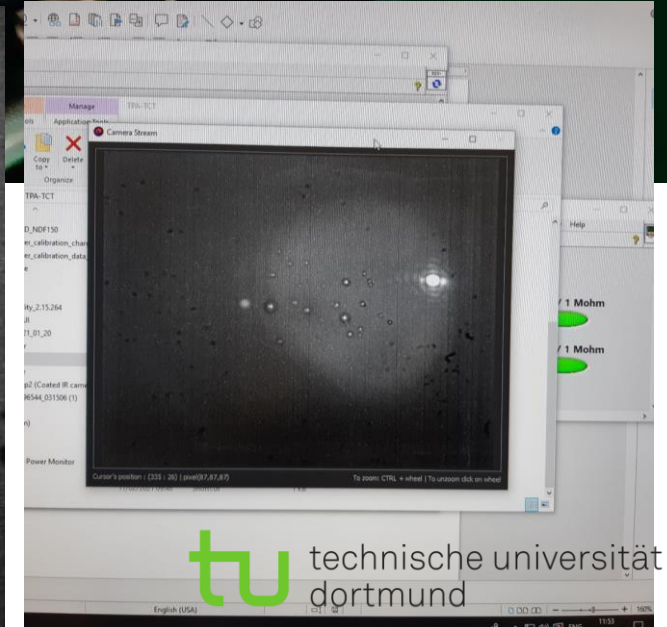
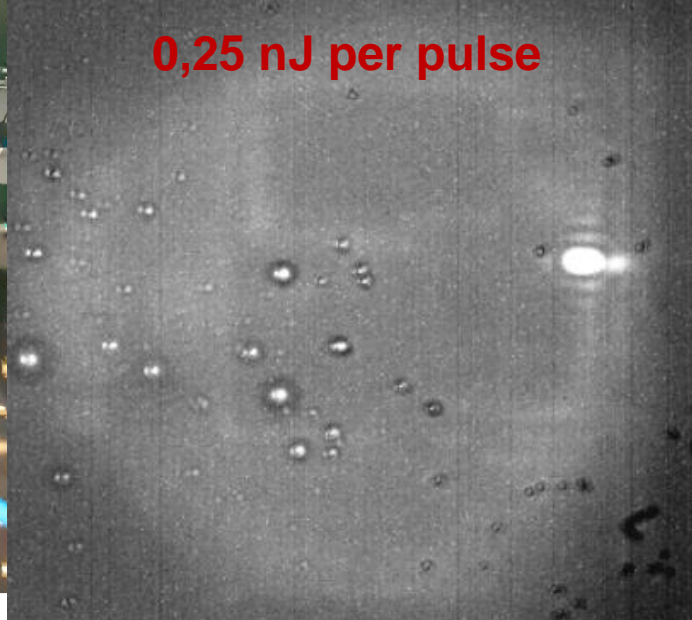


MPW2 + Caribou + FPGA  
in the setup, mounted on a  
costume made rigid carbon  
fibre holder manufactured  
by Ruddy Constanzi (SSD,  
CERN)

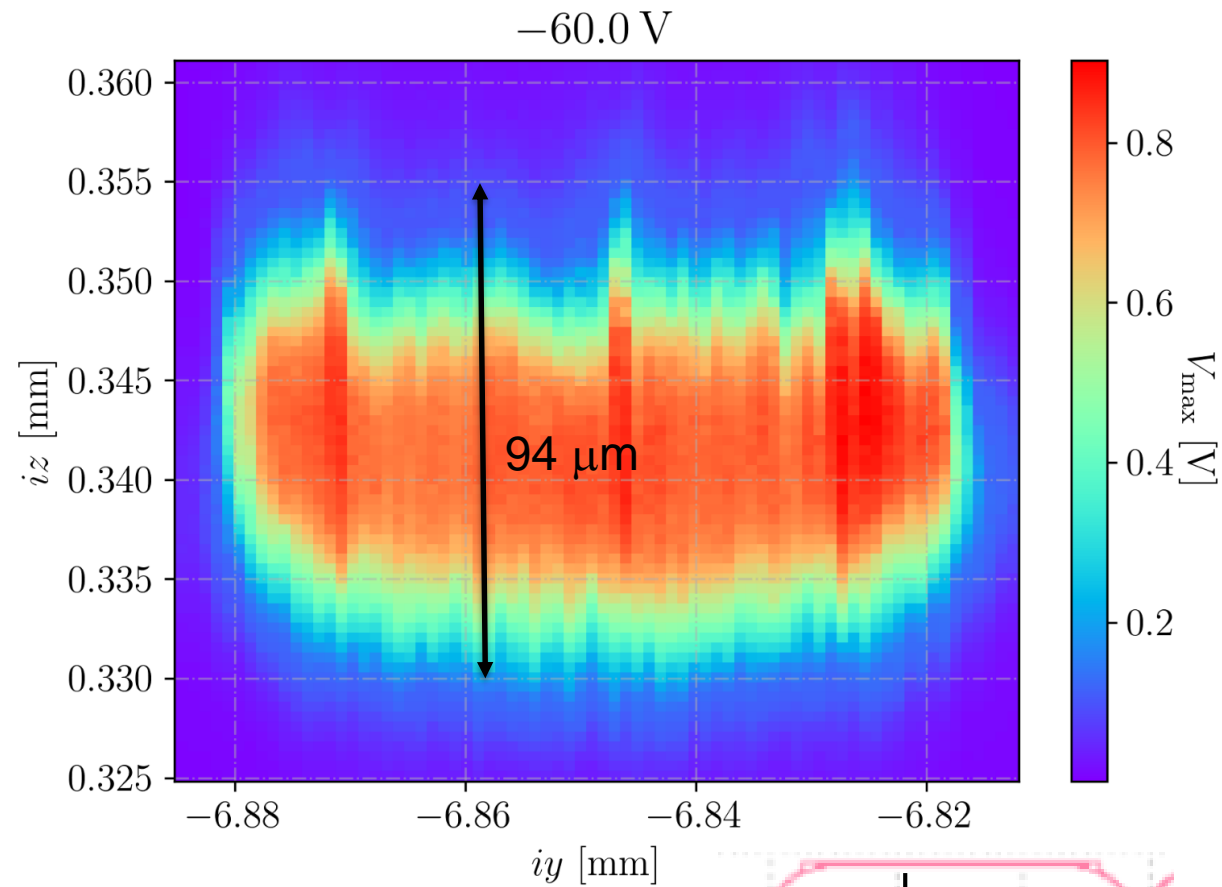
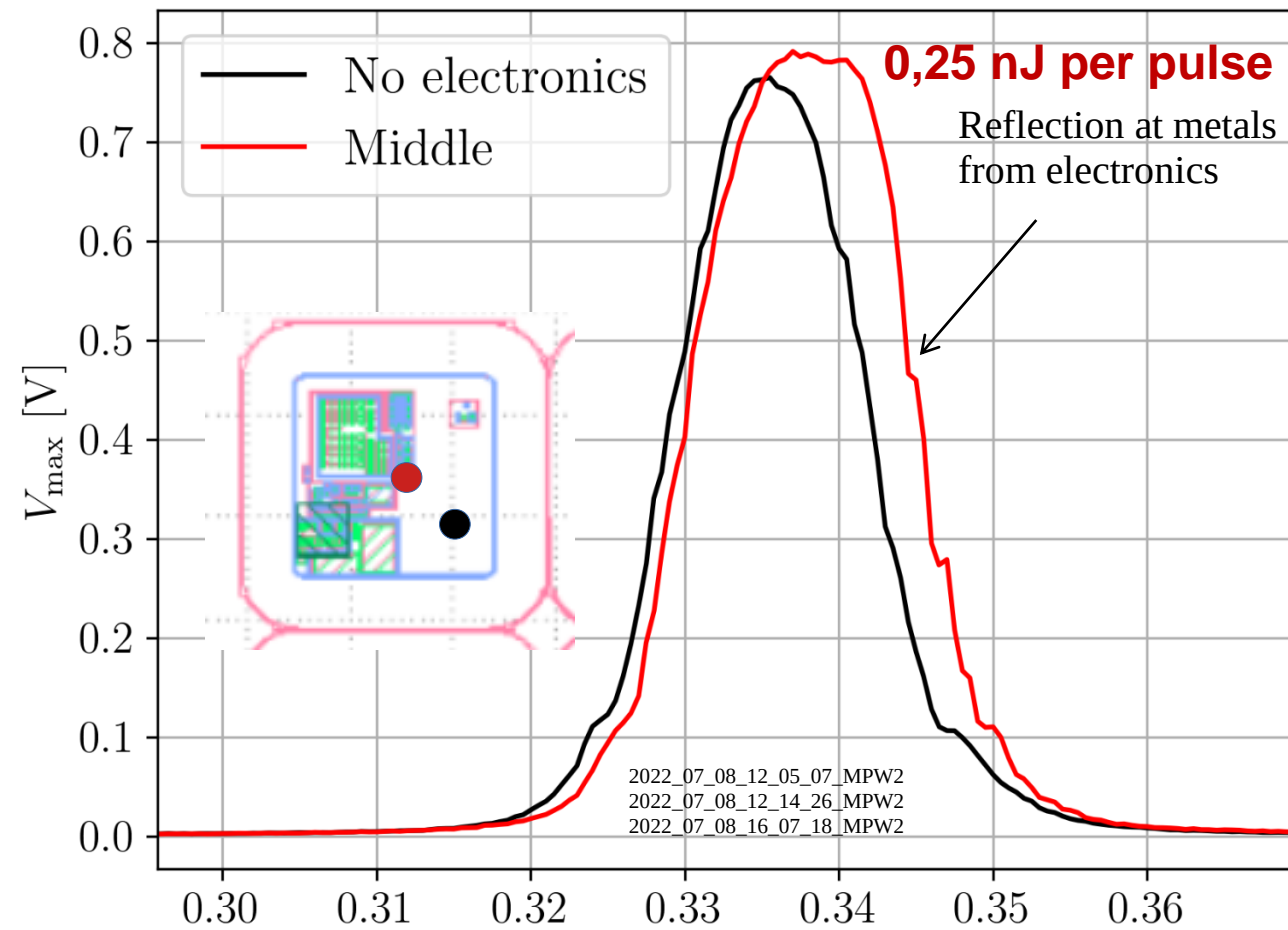
# Locating the target (backside shot)



Pixel 0,0 under the IR microscope (backside)

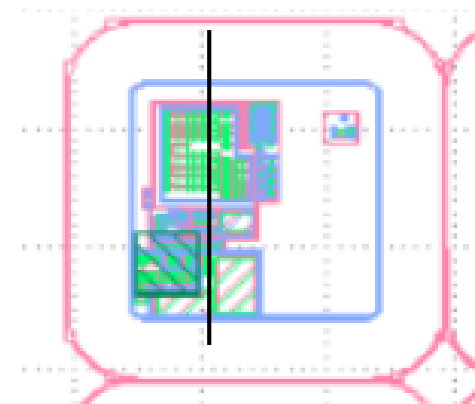


# Pixel 0,0 (APM1)



YZ-Scan across the electronics

- 0  $\mu\text{m}$  top side
- 49  $\mu\text{m}$  middle side
- 94  $\mu\text{m}$  bottom side



$$z_{\text{Si}} = z_{\text{stage}} \cdot \sqrt{\frac{z_{\text{R}} \pi n_{\text{Si}}^3}{z_{\text{R}} \pi n - \lambda n^2 + \lambda}}$$

$$w_0 = 1.5 \mu\text{m} \quad z_{\text{R}} = \frac{\pi w_0^2 n_{\text{Si}}}{\lambda}$$

**z-scale corrected for refraction on Air-Silicon interface factor 3.77 on the stage measurements**

Moritz Wiehe et al., TNS 68(2) 2021



# Pixel 0,0 (APM1)

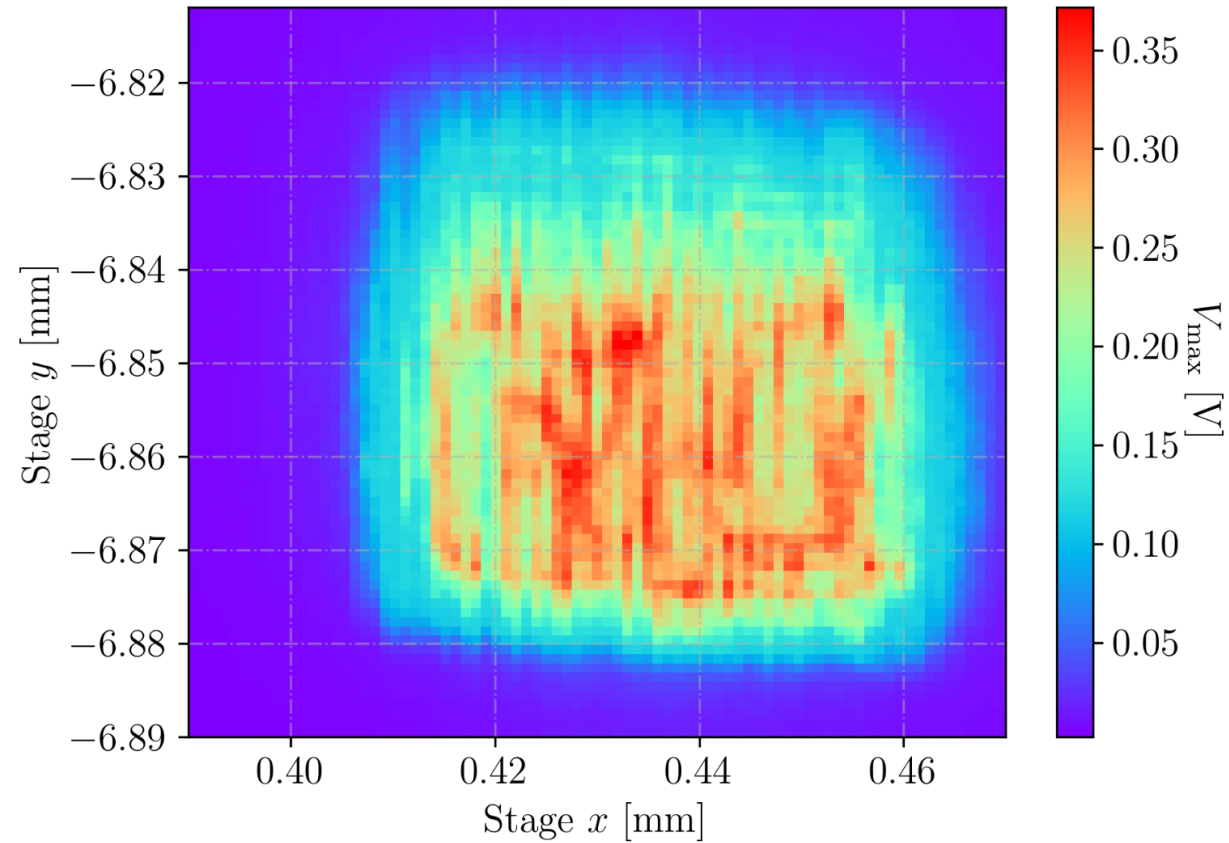
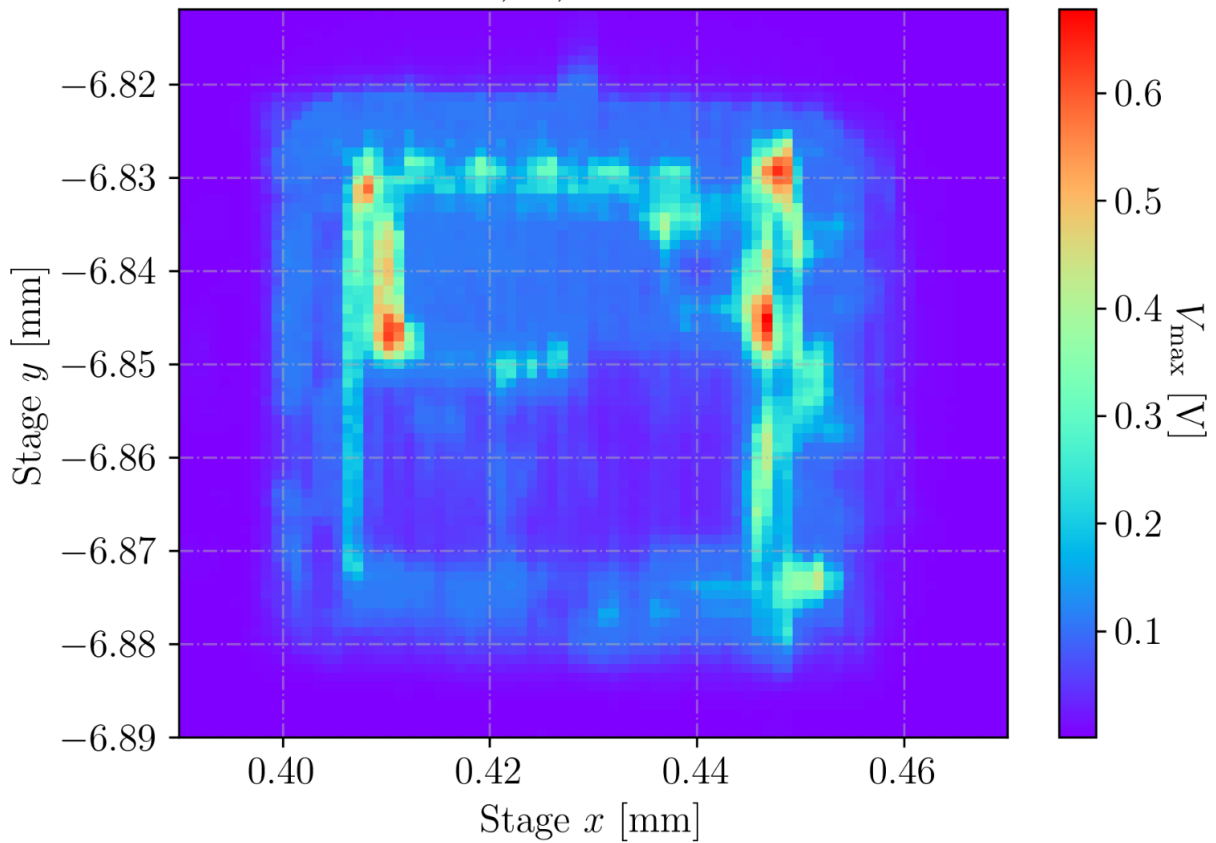
XY-Scan with focus at the top side electronics ( $\pm 3\mu\text{m}$ ) :

Metal layers on the DNWell implant gives bigger signal due to light reflection

XY-Scan with focus at the back side ( $-94\pm 3\mu\text{m}$ ) :

Pixel: r0,c0, Bias:  $-60.0\text{ V}$

Pixel: r0,c0, Bias:  $-60.0\text{ V}$



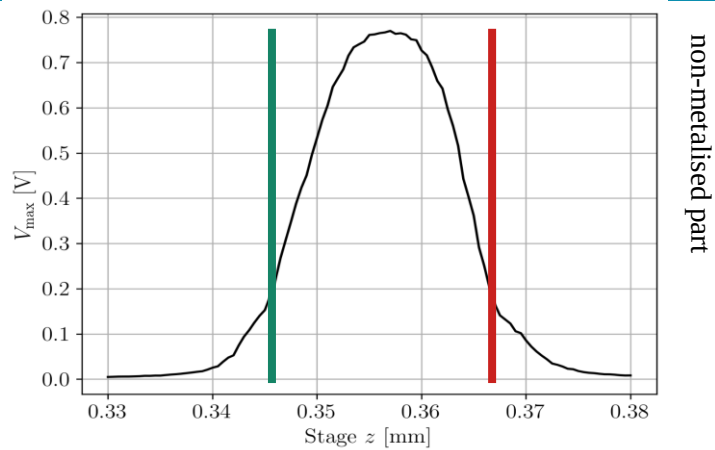
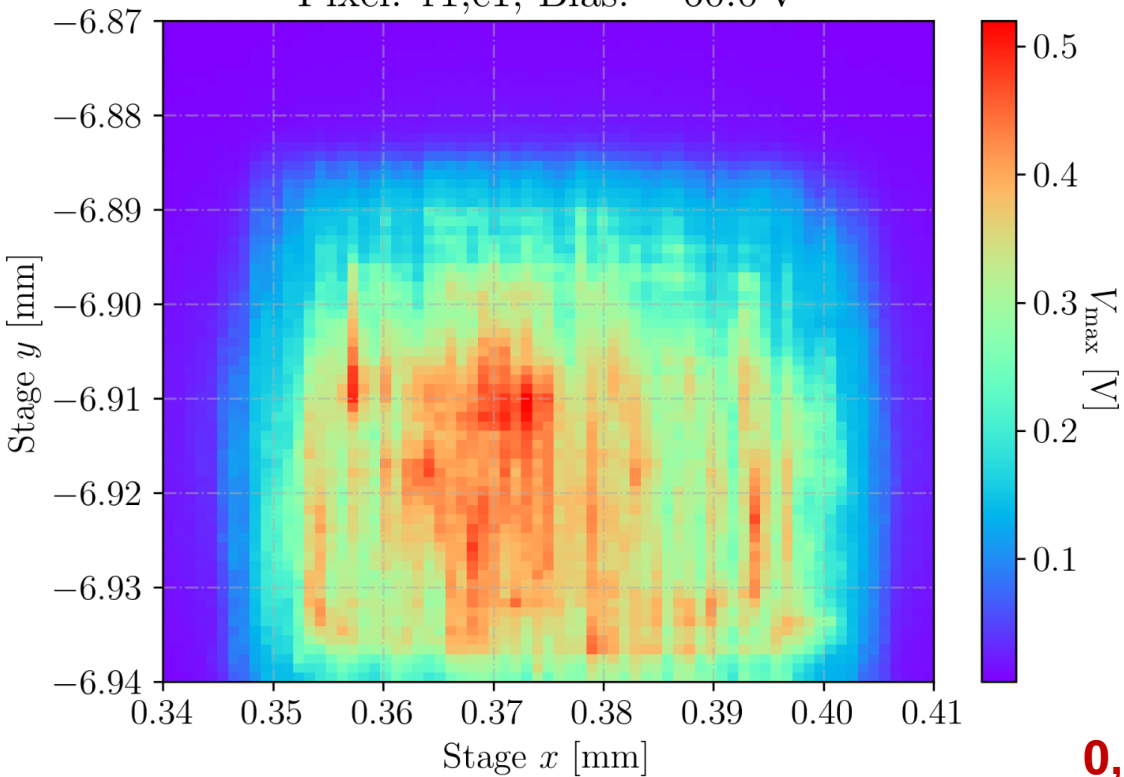
**0,25 nJ per pulse**

# Pixel 1,1 (APM1)

2022\_07\_11\_16\_53\_15\_MPW2  
 2022\_07\_11\_17\_14\_49\_MPW2  
 2022\_07\_11\_19\_31\_19\_MPW2

XY-Scan with focus at the back side  
 (-94  $\mu\text{m}$  with  $\pm 3\mu\text{m}$ ):

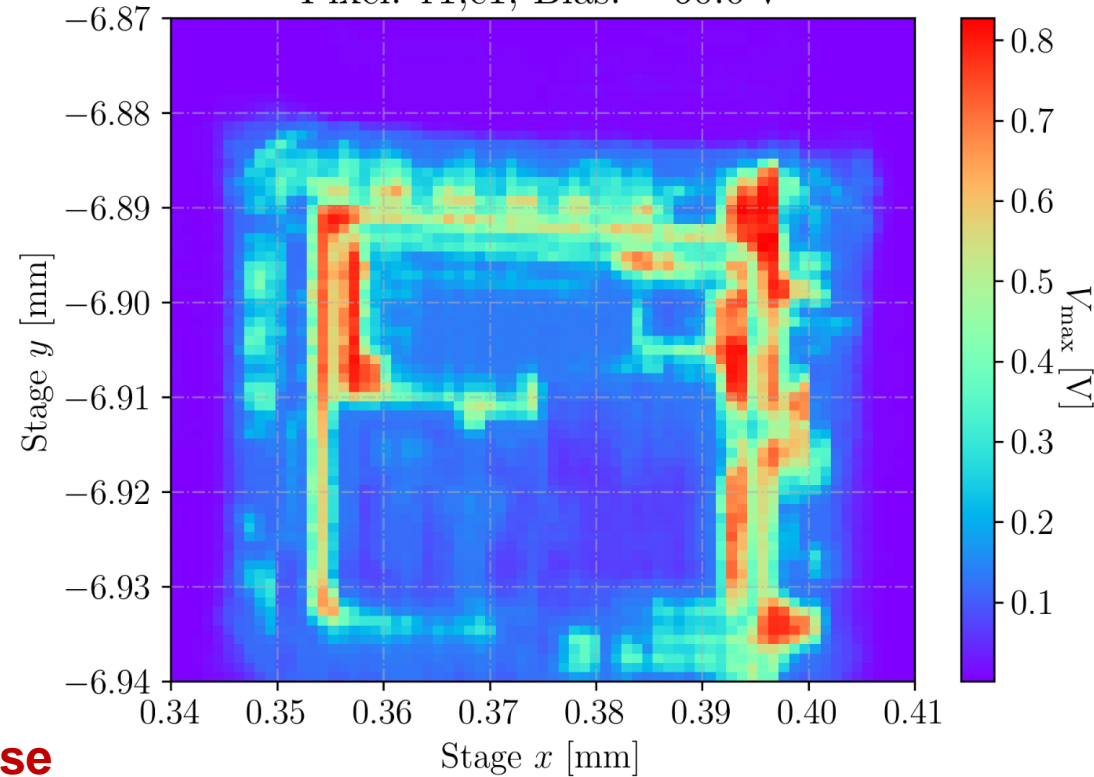
Pixel: r1,c1, Bias: -60.0 V



non-metallised part

XY-Scan with focus at the top side electronics  
 ( $\pm 3\mu\text{m}$ ):

Pixel: r1,c1, Bias: -60.0 V

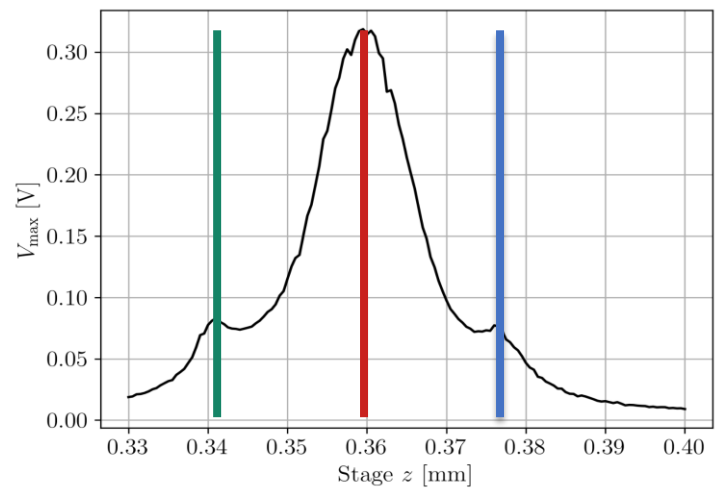
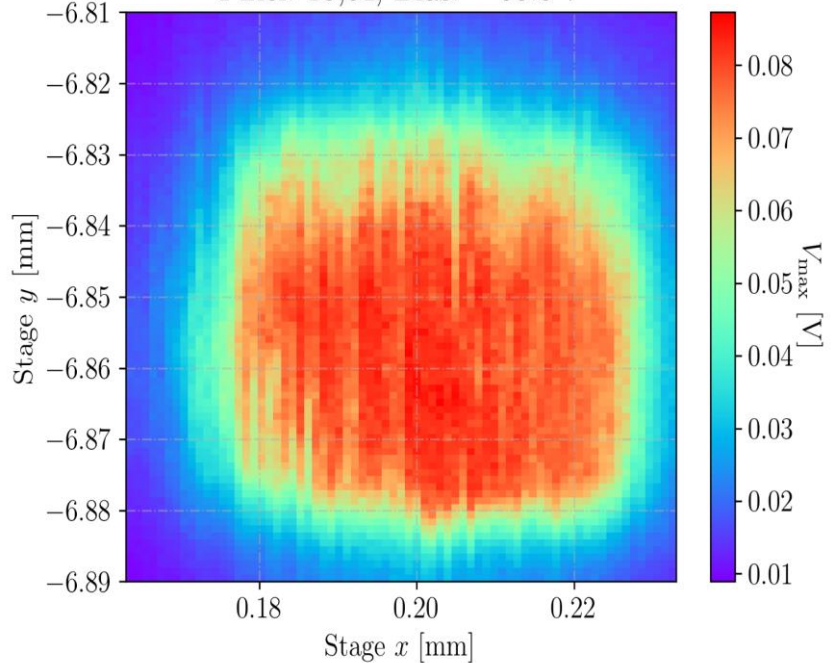


0,25 nJ per pulse

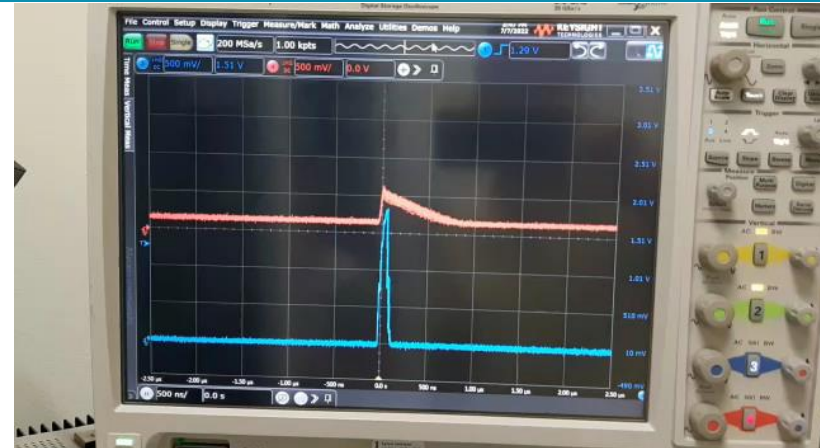
# Pixel 0,4 (APM2)

XY-Scan with focus at the back side ( $-94 \mu\text{m} \pm 3 \mu\text{m}$ ):

Pixel: r0,c4, Bias:  $-60.0 \text{ V}$



non-metallised part

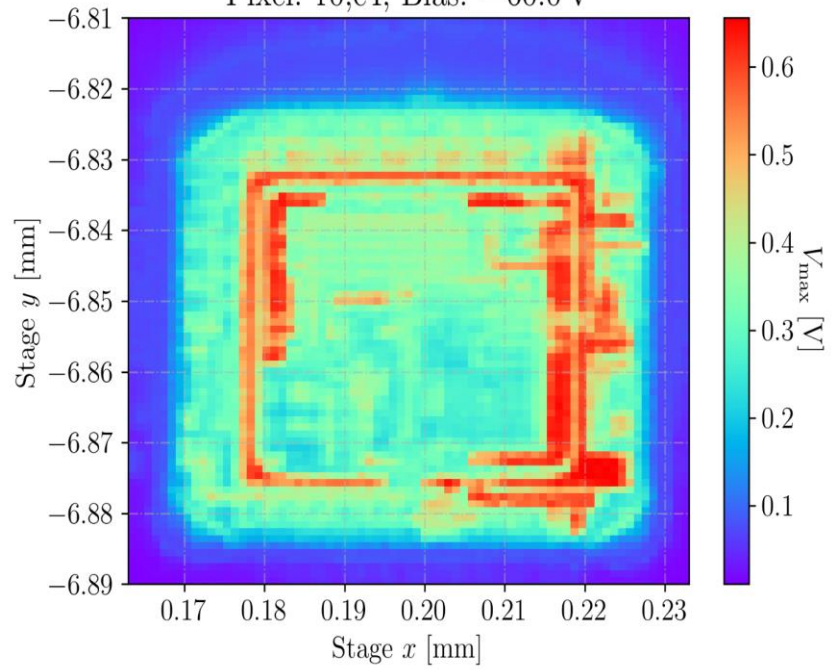


2022\_07\_13\_10\_00\_30\_MPW2  
 2022\_07\_13\_10\_21\_42\_MPW2  
 2022\_07\_13\_11\_35\_35\_MPW2  
 2022\_07\_13\_13\_54\_27\_MPW2

**0,25 nJ per pulse**

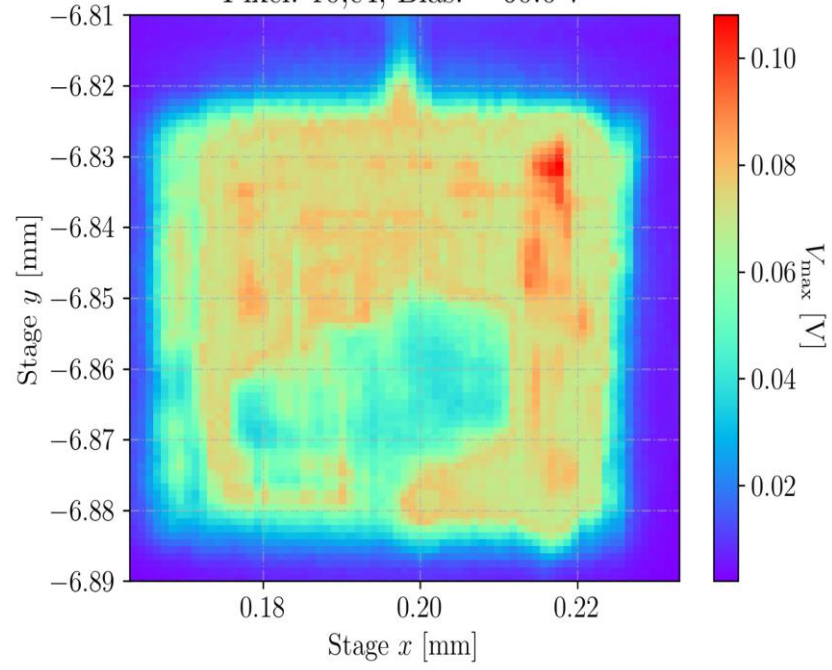
XY-Scan with focus at the middle ( $-49 \mu\text{m} \pm 3 \mu\text{m}$ ):  
 (nwell ring clearly shown in the response)

Pixel: r0,c4, Bias:  $-60.0 \text{ V}$



XY-Scan with focus at the top side ( $\pm 3 \mu\text{m}$ ):

Pixel: r0,c4, Bias:  $-60.0 \text{ V}$



- TPA method can make detailed maps of the electric field, useful to determine the homogeneity of the field
- It is specially appropriate for MAPS because of the in-pixel electronics interference
- ZY maps gives the depletion depth (and the depletion volumen)
  - XY maps gives the CCE in the in-pixel detector volume
  - Probably the best method for quality assesment and with no radiation damage
  - Complementary to the proton microprobe technique, that can be considered the second testing technique for MAPS detectors before going to a full testbeam in a telescope

**Thanks for your attention**  
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